



IPC-1602

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Standard for Printed Board Handling and Storage

Supersedes IPC-1601A

June 2016

An international standard developed by IPC



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Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Standard for Printed Board Handling and Storage

Developed by the Printed Board Storage and Handling Subcommittee
(D-35) of the Rigid Printed Board Committee (D-30) of IPC

Supersedes:

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Users of this publication are encouraged to participate in the
development of future revisions.

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Acknowledgment

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